

H5N2517FN

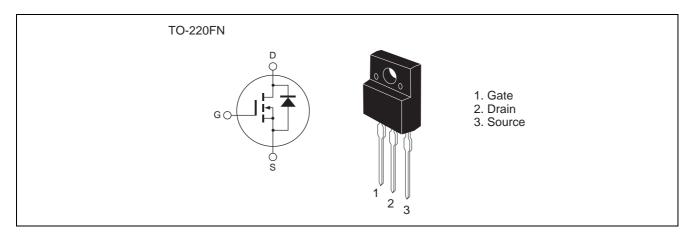
Silicon N Channel MOS FET High Speed Power Switching

REJ03G0371-0100Z Rev.1.00 May.28.2004

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit |
|---|-------------------------------|-------------|------|
| Drain to Source voltage | V _{DSS} | 250 | V |
| Gate to Source voltage | V _{GSS} | ±30 | V |
| Drain current | I _D | 20 | A |
| Drain peak current | I _{D (pulse)} Note1 | 80 | A |
| Body-Drain diode reverse Drain current | I _{DR} | 20 | A |
| Body-Drain diode reverse Drain peak current | I _{DR (pulse)} Note1 | 80 | A |
| Avalanche current | I _{AP} Note3 | 7 | A |
| Avalanche energy | E _{AR} Note3 | 3.0 | mJ |
| Channel dissipation | Pch Note2 | 30 | W |
| Channel to case thermal impedance | θch-c | 4.17 | °C/W |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

Notes: 1. $PW \le 10 \mu s$, duty cycle $\le 1\%$

2. Value at Tc = 25°C

3. STch = 25° C, Tch $\leq 150^{\circ}$ C

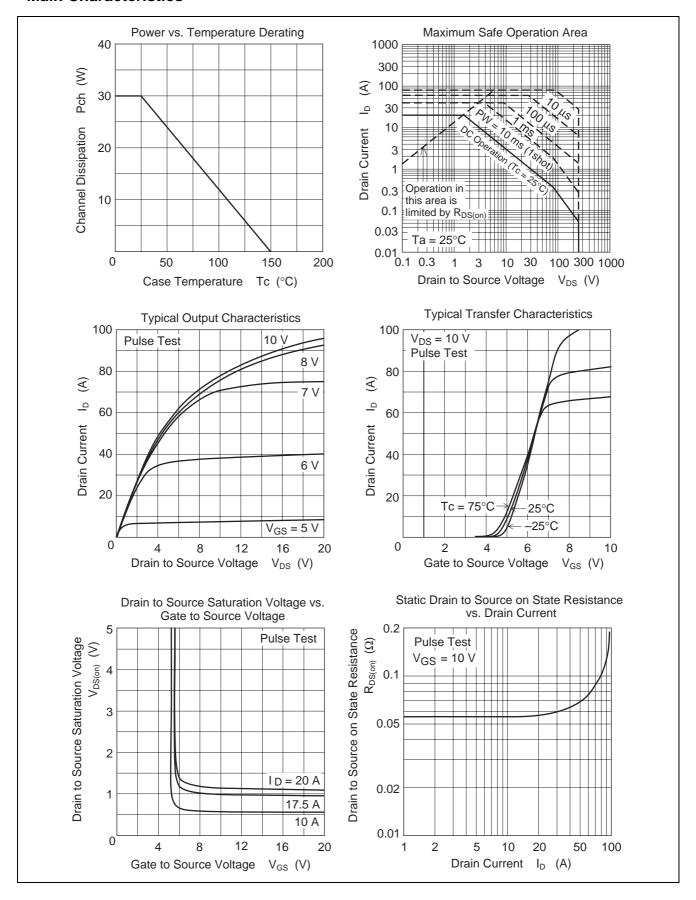
Electrical Characteristics

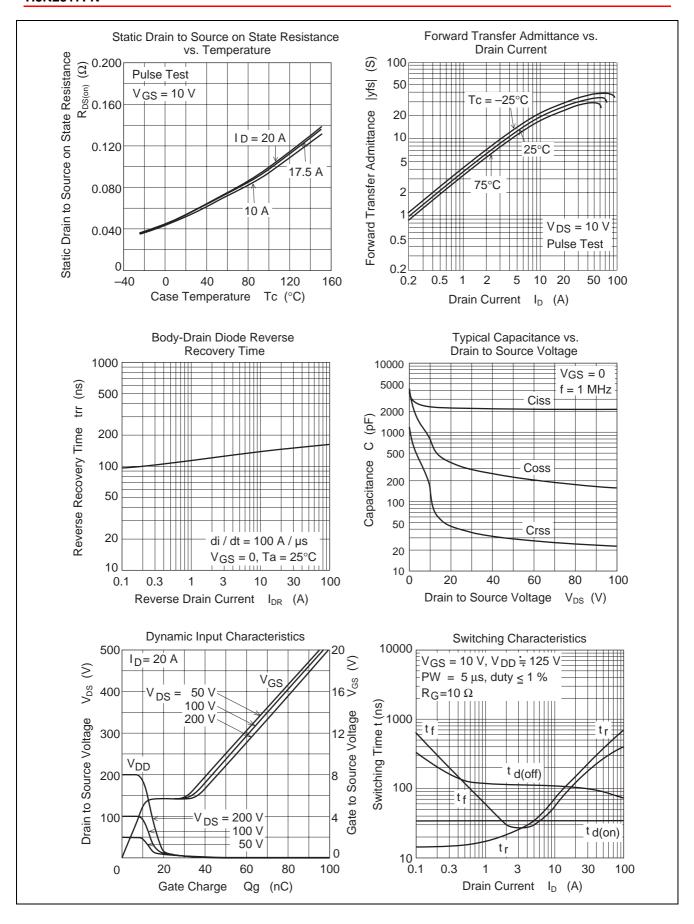
 $(Ta = 25^{\circ}C)$

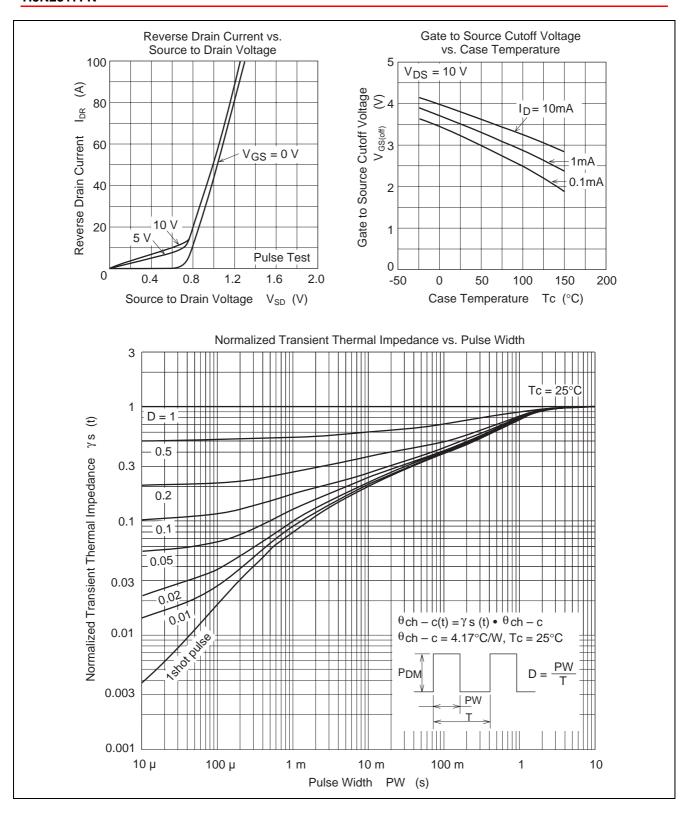
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|--|----------------------|-----|-------|-------|------|---|
| Drain to Source breakdown voltage | $V_{(BR)DSS}$ | 250 | _ | _ | V | $I_D = 10 \text{ mA}, V_{GS} = 0$ |
| Zero Gate voltage drain current | I _{DSS} | _ | _ | 1 | μΑ | $V_{DS} = 250 \text{ V}, V_{GS} = 0$ |
| Gate to Source leak current | I _{GSS} | _ | _ | ±0.1 | μΑ | $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$ |
| Gate to Source cutoff voltage | V _{GS(off)} | 3.0 | _ | 4.0 | ٧ | $V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$ |
| Forward transfer admittance | yfs | 11 | 19 | _ | S | $I_D = 10 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$ |
| Static Drain to Source on state resistance | R _{DS(on)} | _ | 0.055 | 0.072 | Ω | $I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$ |
| Input capacitance | Ciss | _ | 2200 | _ | pF | V _{DS} = 25 V |
| Output capacitance | Coss | _ | 320 | _ | pF | V _{GS} = 0 f = 1 MHz |
| Reverse transfer capacitance | Crss | _ | 40 | _ | pF | |
| Turn-on delay time | td(on) | _ | 35 | _ | ns | I _D = 10 A |
| Rise time | tr | _ | 70 | _ | ns | V _{GS} = 10 V |
| Turn-off delay time | td(off) | _ | 110 | _ | ns | $R_L = 12.5 \Omega$ |
| Fall time | tf | _ | 55 | _ | ns | $Rg = 10 \Omega$ |
| Total Gate charge | Qg | _ | 56 | _ | nC | V _{DD} = 200 V |
| Gate to Source charge | Qgs | _ | 13 | _ | nC | V _{GS} = 10 V I _D = 20 A |
| Gate to Drain charge | Qgd | _ | 26 | _ | nC | |
| Body-Drain diode forward voltage | V_{DF} | _ | 0.9 | 1.5 | V | $I_F = 20 \text{ A}, V_{GS} = 0^{\text{Note4}}$ |
| Body-Drain diode reverse recovery time | trr | _ | 160 | _ | ns | $I_F = 20 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/ μ s |
| Body-Drain diode reverse recovery charge | Qrr | _ | 0.9 | _ | μС | |

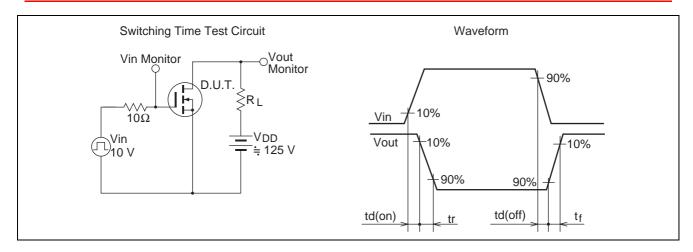
Notes: 4. Pulse test

Main Characteristics

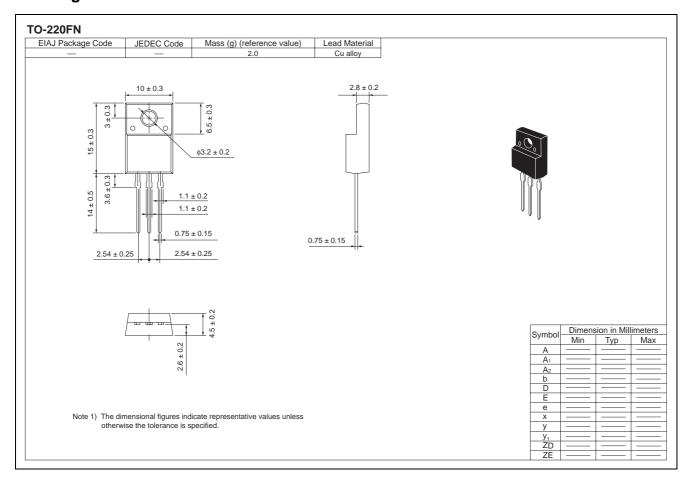








Package Dimensions



Ordering Information

| Part Name | Quantity | Shipping Container |
|-------------|----------|--------------------|
| H5N2517FN-E | 50 pcs | Plastic magazine |

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